Amendments to the Claims

1. *(Currently Amended)* A wafer ~~(1)~~ which wafer ~~(1)~~ comprises a number of exposure fields ~~(2)~~ and which wafer ~~(1)~~ comprises a number of lattice fields ~~(3)~~ in each exposure field ~~(2)~~, wherein each lattice field ~~(3)~~ contains an IC ~~(4)~~ and each IC ~~(4)~~ contains a plurality of IC components, and which wafer ~~(1)~~ comprises a first group ~~(5)~~ of first saw paths ~~(6)~~ and a second group ~~(7)~~ of second saw paths ~~(8)~~, wherein all of the first saw paths ~~(6)~~ of the first group ~~(5)~~ run parallel to a first direction ~~(X)~~ and have a first path width ~~(W1)~~ and wherein all of the second saw paths ~~(8)~~ of the second group ~~(7)~~ run parallel to a second direction ~~(Y)~~ intersecting the first direction ~~(X)~~ and have a second path width ~~(W2)~~, and wherein the first saw paths ~~(6)~~ and the second saw paths ~~(8)~~ are provided and designed for a subsequent segregation of the lattice fields ~~(3)~~ and the ICs ~~(4)~~ contained therein, and wherein in each exposure field ~~(2)~~ at least two control module fields ~~(A1, A2, B1, B2, C1, C2, D1, D2)~~ are provided, each of which control module fields ~~(A1, A2, B1, B2, C1, C2, D1, D2)~~ runs parallel to the first direction ~~(X)~~ and thus to the first saw paths ~~(6)~~ and contains at least one optical control module ~~(OCM-A1, OCM-A2, OCM-B1, OCM-B2, OCM-C1, OCM-C2, OCM-D1, OCM-D2)~~, wherein each control module ~~(OCM-A1, OCM-A2, OCM-B1, OCM-B2, OCM-C1, OCM-C2, OCM-D1, OCM-D2)~~ contains a plurality of control module components ~~(10, 11, 12, 13, 14, 15, 16, 17, 18)~~, and wherein each control module field ~~(A1, A2, B1, B2, C1, C2, D1, D2)~~ within an exposure field ~~(2)~~ comprises a plurality of control module field sections ~~(A11, A12, ...A1N and A21, A22, ... A2N and B11, B12, ...B1N and B21, B22, ...B2N and C1N and C2N and D1N and D2N)~~ and is distributed among several lattice grids ~~(3)~~, and wherein each control module field section ~~(A11 to D2N)~~ is located in a lattice field ~~(3)~~ and contains at least one control module component ~~(10, 11, 12, 13, 14, 15, 16, 17, 18).~~

2. *(Currently Amended)* A wafer ~~(1)~~ as claimed in claim 1, wherein each control module field section ~~(A11 to D2N)~~ in each lattice field ~~(3)~~ is located in the same position, in which position the IC ~~(4)~~ in the lattice field ~~(3)~~ in question does not have any IC components.

3. *(Currently Amended)* A wafer ~~(1)~~ as claimed in claim 1, wherein the at least two control module fields ~~(A1, A2, B1, B2, C1, C2, D1, D2)~~ of each exposure field ~~(2)~~ are arranged at an average distance ~~(K)~~ from one another extending in the second direction ~~(Y)~~, which average distance ~~(K)~~ is equal to at least a quarter of the side length ~~(L)~~ of a side ~~(M)~~ of the exposure field ~~(2)~~ which extends in the second direction ~~(Y)~~.

4. *(Currently Amended)* Wafer ~~(1)~~ as claimed in claim 3, wherein the average distance ~~(K)~~ is equal to the whole side length ~~(L)~~ of a side ~~(M)~~ of the exposure field ~~(2)~~, which area extends in the second direction ~~(Y)~~ minus the side length ~~(N)~~ of a side ~~(P)~~ of a lattice field ~~(3)~~ which extends in the second direction ~~(Y)~~.